

L Number	Hits	Search Text	DB	Time stamp
1	87	stack near4 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 09:31
2	6	(stack near4 heat adj sink.ti,ab,clm.) and (rubber or elastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 10:14
3	5	(stack near4 heat adj sink.ti,ab,clm.) and (rubber or elastic or spacer) near12 (insulat\$3 or isolat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 10:15
8	29	riser near6 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 11:04
9	2	riser near10 heat adj sink near10 (liquid or flow or fluid or coolant or water)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 11:05
10	28	riser near10 (liquid or flow or fluid or coolant or water) and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 11:53
13	2	("5794839").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 13:19
14	7	semiconductor adj laser.ti,ab,clm. and heat adj sink.ti,ab,clm. and (stack or stacked) near3 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 14:10
15	1	heat adj sink.ti,ab,clm. and (stack or stacked) near3 heat adj sink and (upper adj electrode near20 lower adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 14:08
16	2	semiconductor.ti,ab,clm. and heat adj sink.ti,ab,clm. and (stack or stacked) adj heat adj "sinks" and (top upper) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 14:22
20	36		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 14:28
21	9		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 15:21
23	174	257/625	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:09

24	8124	((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:23
26	1	((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (riser guide guiding) near12 (flow liquid water coolant) and (stack stacked) near2 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:13
27	2	((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and stacked adj heat adj sinks	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:39
28	10	((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:45
32	0	((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks) and (first upper top) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:46
33	2	((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:49
34	0	stacked adj heat adj sinks.ti,ab,clm. and semiconductor adj2 (element device) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:51
35	4	(stack stacked stacked) near12 heat adj sinks and semiconductor adj2 (element device) and ((top upper) adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:31
36	2	("4631573").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 17:31
37	3	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 17:31
38	1	stacked.ti,ab,clm. and heat adj sink.ti,ab,clm. and (electronic or semiconductor) adj (device or element) and "in series"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:34
39	0	semiconductor adj laser.ti,ab,clm. and (372/4\$1.ccls. or 372/50.ccls.) and stacked and "in series"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:35
40	74	semiconductor adj laser.ti,ab,clm. and (372/4\$1.ccls. or 372/50.ccls.) and stacked and series	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:53

41	8	stacked near3 active near3 region near3 monolithic near3 laser near3 array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:55
42	2	("5157680").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:55
43	20	stacked near12 active near12 laser near12 array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 20:35
44	2	("4791634").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:07
45	2	("6144683").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:08
46	0	("jp-8181392\$-\$\$.did.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:09
47	2	jp-08181392\$-\$\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:09
48	0	bell.in. and morrison.in. and law.in. and malcolm.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:11
49	1	gb-1597829\$-\$\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:12
-	2	jp-09102568\$-\$\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 09:31
-	2	jp-08227953\$-\$\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 16:22
-	2	jp-08139479\$-\$\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 16:24
-	3	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 16:24
-	2008	((372/34) or (372/35) or (372/36)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:24

-	996	heat adj sink.ti. and 257/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 07:45
-	33	heat adj sink.ti. and liquid.ti,ab. and 257/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 15:28
-	20	((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and laser.ti,ab. and heat adj sink.ti,ab. and (liquid or water).ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 08:27
-	8	(US-6307871-\$ or US-5801442-\$ or US-4791634-\$ or US-4712609-\$ or US-3764935-\$).did. or (US-20010004370-\$).did. or (JP-02257683-\$ or JP-63073584-\$).did.	USPAT; US-PGPUB; JPO	2002/08/07 08:49
-	388	(257/365).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/08 15:44
-	6068	((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:50
-	307	((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:52
-	110	((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:53
-	63	(((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:55
-	40	(((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))) and semiconductor	USPAT	2002/08/09 12:56
-	44	(((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 13:32
-	1	heat adj sink.ti. and liquid.ti,ab. and 372/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 15:29

-	33	heat adj sink.ti. and 372/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 15:29
-	10026	heat adj sink and upper near12 lower	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:24
-	710	heat adj sink.ti. and upper near12 lower	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:25
-	70	heat adj sink.ti. and upper near12 lower near12 (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:26
-	30	heat adj sink.ti. and upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:31
-	2	heat adj sink.ti. and (groove or trench) near12 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:33
-	2	heat adj sink.ti,ab. and (groove or trench) near12 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:34
-	2	heat adj sink.ti,ab. and (groove or trench) near18 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:35
-	4	heat adj sink.ti,ab. and (groove or trench) near18 upper near6 lower near6 (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:52
-	6	heat adj sink.ti,ab. and (groove or trench) near18 ((upper near18 lower) near18 (face or main adj surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:54
-	4163	((257/712) or (257/713) or (257/714) or (257/715)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 14:08
-	1156	(372/34).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:25
-	423	(372/35).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:25
-	661	(372/36).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26

-	1884	(257/712).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	958	(257/713).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	1193	(257/714).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	493	(257/715).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	6144	((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:27
-	4269	((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.)) and (heat adj removal or heat adj sink or coolant or cooling)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:28
-	3590	((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.)) and (heat adj removal or heat adj sink or coolant or cooling).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:29
-	1280	((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.)) and (heat adj removal or heat adj sink or coolant or cooling).ti,ab,clm. and liquid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:29
-	263	((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.)) and (heat adj removal or heat adj sink or coolant or cooling).ti,ab,clm. and liquid and (groove or trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:30
-	27	(US-6198758-\$ or US-6310900-\$ or US-3654528-\$ or US-4807022-\$ or US-5729052-\$ or US-5783862-\$ or US-5864176-\$ or US-5918665-\$ or US-6157077-\$ or US-6274912-\$ or US-6347050-\$ or US-5801442-\$ or US-4712609-\$ or US-3764935-\$ or US-5241450-\$ or US-4791634-\$ or US-5812570-\$ or US-6307871-\$).did. or (US-20010004370-\$).did. or (JP-02257683-\$ or JP-63073584-\$ or JP-09102568-\$ or JP-08227953-\$ or JP-08139479-\$).did. or (JP-09102568-\$ or EP-715352-\$ or JP-08139479-\$).did.	USPAT; US-PGPUB; JPO; DERWENT	2002/08/23 18:39

5	((US-6198758-\$ or US-6310900-\$ or US-3654528-\$ or US-4807022-\$ or US-5729052-\$ or US-5783862-\$ or US-5864176-\$ or US-5918665-\$ or US-6157077-\$ or US-6274912-\$ or US-6347050-\$ or US-5801442-\$ or US-4712609-\$ or US-3764935-\$ or US-5241450-\$ or US-4791634-\$ or US-5812570-\$ or US-6307871-\$).did. or (US-20010004370-\$).did. or (JP-02257683-\$ or JP-63073584-\$ or JP-09102568-\$ or JP-08227953-\$ or JP-08139479-\$).did. or (JP-09102568-\$ or EP-715352-\$ or JP-08139479-\$).did.) and laser adj diode ("4791634").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 18:39
2	jp-8227953\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 14:12
0	jp-8227953\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 14:13
2	jp-08227953\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 14:13
21	zengerle.in. and heat	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 15:25
4	zengerle.in. and power adj semiconductor adj component	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 15:26
4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 14:06
127	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:18
103	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:24
103	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow) and heat adj sink.ti,ab,clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:24

-	4	((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow) and (groove or slit) near12 heat adj sink	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:32
-	5	((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow) and (groove or slit) near12 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:48
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:49
-	1627	(257/678).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:15
-	36	((257/678).CCLS.) and heat adj sink.ti,ab,clm. and (liquid or water or flow or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:39
-	109	hayashi.in. and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:40
-	18	hayashi.in. and laser.ti,ab,clm. and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:42
-	2	jp-09102568\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:54
-	1442	heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:56
-	3	lsi and (heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:59
-	2	(heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.) and liquid adj coolant.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:00
-	4	(heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.) and liquid adj coolant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:09

-	491	semiconductor adj laser near6 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:09
-	249	semiconductor adj laser near3 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:11
-	1	(semiconductor adj laser near3 heat adj sink.ti,ab,clm.) and liquid adj coolant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:12
-	35	(semiconductor adj laser near3 heat adj sink.ti,ab,clm.) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:03
-	2	jp-08227953\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:14
-	2	("3351698").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:22
-	0	("heat adj sink near20 laser near20 electrode near20 copper").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:22
-	19	heat adj sink near20 laser near20 electrode near20 copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:53
-	0	top adj electrode near12 bottom adj electrode near20 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:55
-	44	"electrodes" near12 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:56
-	29	"electrodes" near6 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:56
-	8	"electrodes" near3 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:02
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:02
-	2118	heat adj sink near12 electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:07

-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:18
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:34
-	2	guiding adj (hole or through-hole or aperture) near12 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:51
-	115	(hole or through-hole or aperture) near12 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:53
-	103	(hole or through-hole or aperture) near6 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:55
-	57	(hole or through-hole or aperture) near3 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:56
-	3	(hole or through-hole or aperture) near3 (guide or guiding) near12 heat adj sink near12 (liquid or water or coolant) and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:59
-	2	jp-09102568\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:00
-	2	jp-08227953\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:01
-	3	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:30
-	0	("heat adj sink near12 (leak or leakage or leaking) near12 rubber").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:30
-	0	heat adj sink near12 (leak or leakage or leaking) near12 rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:31
-	0	heat adj sink near12 (leak or leakage or leaking) near12 (elastic rubber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:32
-	20	heat adj sink near12 (leak or leakage or leaking) near12 (elastic rubber insulating insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 21:09

2	jp-08181392\$-\$.did.	USPAT;	2003/05/12
		US-PGPUB;	21:09
		EPO; JPO;	
		DERWENT;	
		IBM TDB	